



News Release

FOR IMMEDIATE RELEASE

BTU Introduces High-Yield Reflow Technologies for Advanced Packaging at SEMICON Taiwan

WESTFORD, Mass., August 26, 2026 – BTU International, Inc., a leading supplier of advanced thermal processing equipment for the electronics manufacturing and semiconductor industries, will showcase its latest high-yield reflow technologies at SEMICON Taiwan in Booth I2516, with a focus on advanced packaging and other high-density applications. BTU's booth is collocated with trusted representative, CohPros International.

Visitors will have the opportunity to see the **Aurora Vacuum™ Reflow Oven**, BTU's next-generation vacuum reflow platform designed to deliver exceptional solder quality, maximum throughput and higher manufacturing yields for advanced electronic assemblies. Developed for increasingly complex PCB assemblies, the system combines advanced process control with a high-throughput architecture optimized for volume production.



BTU will also introduce its new fluxless **Formic Acid Reflow capability**, developed to support the increasing demands of advanced semiconductor packaging, power devices and high-reliability electronic assemblies. The process option enables fluxless soldering and uses concentrated, targeted formic process zones to deliver the chemistry where oxide reduction is required, reducing overall formic acid consumption while maintaining effective oxide removal. The Formic Acid Reflow capability is available across multiple BTU reflow platforms and is suited to applications including advanced packaging, flip chip, power devices and wafer-level packaging.

Both systems have been optimized for high-volume and low vibration processing enabling the scale up of advanced semiconductor packaging devices.

"As the semiconductor and electronics industries continue to scale to meet unprecedented demand, manufacturers need process technologies that improve both yield and productivity simultaneously. BTU's new vacuum reflow and formic acid fluxless reflow solutions are designed to remove barriers to scale by enhancing solder joint quality, reducing process variability, and increasing production throughput," said Rob DiMatteo, General Manager of BTU International. "As advanced packaging and power device applications become more demanding, these technologies provide the process performance manufacturers need to achieve higher yields and operational efficiency. We are proud to deliver enabling solutions that help our customers accelerate production, improve profitability, and support the next phase of growth," added DiMatteo.

Visit BTU International in Booth I2516 to learn more about its latest reflow technologies.

More information about BTU International is available at www.btu.com.

About BTU International

BTU International, a wholly-owned subsidiary of Amtech Group (Nasdaq: ASYS), is a global supplier and technology leader of advanced thermal processing equipment in the electronics manufacturing market. BTU's high-performance reflow ovens are used in the production of SMT printed circuit board assemblies and in semiconductor packaging processes. BTU also specializes in precision controlled, high-temperature belt furnaces for a wide range of custom applications, such as brazing, direct bond copper (DBC), diffusion, and sintering. BTU has operations in Westford, Massachusetts, and Shanghai, China, with direct sales and service in the U.S.A., Asia and Europe. Information about BTU International is available at www.btu.com.

###

Company Contact:

Rob DiMatteo
General Manager
BTU International, Inc.
Phone: +1- (978) 667-4111

Media Contact:

Megan Wendling
MW Associates
Phone: +1-(239) 530-8790